

MW-G-VSP

- HS-VSP 銅箔低稜線特性具極佳的絕緣效果與具優越的蝕刻性之符合新一代環保要求之電解銅箔。
HS-VSP foil with very low profile to have excellent insulation result and good etchability, and comply with environment regulation.
- 具低的稜線為應用於高速訊號傳輸板最佳銅箔材料。
Very low profile of MW-G-VSP makes it an excellent material to apply to high speed transmission board.

用途/Application

- 高速訊號傳輸板
/HSD (High speed digital)

結構/Composition

生產地點/Production Site

- 台灣 / Taiwan

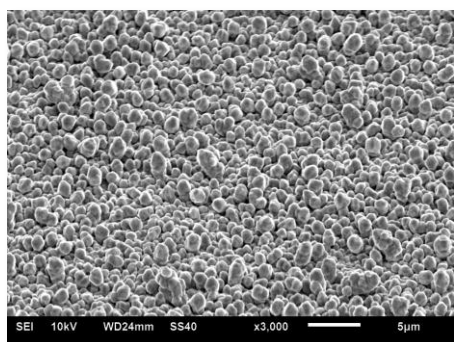
特性代表值/Representative data

	μm	Rz (μm)	Tensile Strength (N/mm ²)	Elongation (%)	Peel Strength (kg/cm)
MW-G-VSP	18	2.5	350	8	1.0
	35	2.5	350	16	1.3
	70	2.5	350	19	1.5

※上述表列為代表性數據非保證值。

This is representative data, not guarantee.

處理面/Laminate side



阻劑面 / resist side

